ABSTRACT

A resin molding apparatus performs compression molding. This resin molding apparatus includes a molding die, a clamping mechanism, and a sensor. The molding die includes an upper die and a lower die facing the upper die. The clamping mechanism clamps the molding die. Clamping is performed in a state in which an object to be molded is placed on a lower surface of the upper die and a resin is placed on an upper surface of the lower die. The object to be molded includes a substrate and a plurality of electronic components placed on the substrate. The plurality of electronic components are located under the substrate in a state in which the object to be molded is placed on the lower surface of the upper die. The sensor detects that at least one of the electronic components has fallen downward from the substrate in a state in which the object to be molded is placed on the lower surface of the upper die.

(Fig. 1)